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**Fabrication Method:**

Molded

**Body Mounting Hole Accommodation Diameter:**

0.320 inches

**Mounting Hole Style:**

Round, flatted

**Specific Equipment Accommodated:**

Semiconductor device

**Contact Material:**

Copper alloy

**Contact Surface Treatment:**

Gold and silver

**Accommodated Contact Quantity:**

3

**Polarization Type:**

Contact position

**Distance From Flatted Portion To Opposite Surface:**

0.280 inches

**Mounting Method:**

Body through hole

**Mounting Type For Which Designed:**

Chassis

**Contact Position Arrangement Style:**

Circular irregular 0.200 inch

**Precious Material And Location:**

Contact surfaces gold and contact surfaces silver

**Precious Material And Weight:**

0.015 gold grains, troy and 0.015 silver grains, troy

**Precious Material:**

Gold and silver

**Terminal Type And Quantity:**

3 tab, solder lug

**Shelf Life:**

N/a

**Unit Of Measure:**

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**Demilitarization:**

No

**Fiig:**

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